			DB	Time stamp
L	Hits	Search Text	DB	-
Number 5	1946	(laminar with (flow or flowing)) and	USPAT	2004/03/03
	1310	semiconductor		13:04
6	2979	(laminar with (flow or flowing)) and	USPAT;	2004/03/03
		semiconductor	US-PGPUB;	13:08
			EPO; JPO;	, <u>f</u>
			DERWENT;	
			IBM_TDB USPAT;	2004/03/03
7	2139	((laminar with (flow or flowing)) and	US-PGPUB;	13:05
		semiconductor ) and @ay<=2000	EPO; JPO;	13.33
			DERWENT;	
	i		IBM TDB	
8	180	(((laminar with (flow or flowing)) and	USPĀT;	2004/03/03
0	100	semiconductor ) and @ay<=2000) and	US-PGPUB;	13:06
		(polish or polishing)	EPO; JPO;	
		•	DERWENT;	
			IBM_TDB	2004/02/03
9	8	schwab-Gunter.in.	USPAT; US-PGPUB;	2004/03/03
]			EPO; JPO;	15.00
			DERWENT;	
			IBM TDB	
10	15	   Franke-Helmut.in.	USPAT;	2004/03/03
10	13	Planke neimue.in.	US-PGPUB;	13:06
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
11	1	Schofberger-Manfred.in.	USPAT;	2004/03/03
			US-PGPUB;	13:07
			EPO; JPO; DERWENT;	
			IBM TDB	
		6596599.pn. and (shield same edge)	USPAT;	2004/03/03
12	0	6596599.pn. and (shrerd same edge)	US-PGPUB;	13:07
1	•		EPO; JPO;	
			DERWENT;	
			IBM_TDB	
13	0	6596599.pn. and shield	USPAT;	2004/03/03
			US-PGPUB;	13:07
			EPO; JPO; DERWENT;	
-			IBM TDB	
	0.150	((laminar with (flow or flowing)) and	USPAT;	2004/03/03
14	2153	semiconductor ) not plasma	US-PGPUB;	13:08
		Semiconductor / not prasma	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
15	913	(((laminar with (flow or flowing)) and	USPAT;	2004/03/03
		semiconductor ) not plasma) and edge	US-PGPUB;	13:08
			EPO; JPO;	
			DERWENT;	
		(5)	IBM_TDB USPAT;	2004/03/03
16	42	((((laminar with (flow or flowing)) and	USPAT; US-PGPUB;	13:09
	1	semiconductor ) not plasma) and edge) and ((etch or etching) same laminar)	EPO; JPO;	13.03
		((etch or etching) same familiar)	DERWENT;	
			IBM TDB	
	1		_l,	